

#2

**INFORMATION DISCLOSURE STATEMENT** 

Case Name.
Sorial No.
Applicant:
Filing Date:

Group:

H.S. Fetterman 7-17

Applicant: H.S. Fetterman, et al.

10/007904 10/007904 10/31/01

**U.S. PATENT DOCUMENTS** 

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date
EP.	AA	4,918,377	Apr. 1990	Buehler et al.	324	691	12/5/88
EP.	AB	4,319,396	Dec. 1979	Law et al.	29	571	12/28/79
D	AC	Re. 32,625	Mar. 1988	Schwarz et al.	374	57	8/18/86
El	AD	4,024,561	May 1977	Ghatalia	357	23	4/1/76
EP	AE	4,801,869	Jan. 1989	Sprogis	324	73	4/27/87
Š)	AF	3,974,443	Aug. 1976	Thomas	324	64	1/2/75
50	AG	5,268,329	Dec. 1993	Chittipeddi et al.	437	195	11/8/91
El	AH	5,798,300	Aug. 1998	Chittipeddi et al.	438	627	5/15/97
3	Al	5,972,179	Oct. 1999	Chittipeddi et al.	204	192.17	9/30/97
ΣÝ	AJ	5,244,839	Sep. 1993	Baker et al.	437	205	6/18/91
EP	AK	5,318,924	Jun. 1994	Lin et al.	437	192	1/22/93
20	AL	5,300,307	Apr. 1994	Frear et al.	427	96	9/14/92
80	AM	5,264,377	Nov. 1993	Chesire et al.	437	. 8	4/3/92
21	AN	5,049,811	Sep. 1991	Dreyer et al.	324	158	7/2/90
ZP	AO	5,514,974	May 1996	Bouldin	324	763	10/12/94
-, .					<u> </u>		
	]				1		

## **FOREIGN PATENT DOCUMENTS**

		Document Number	Date	Country	Class	Subclass	Translation
·[							

OTHER (including Author, Title, Date, Pertinent Pages, etc.)

El El	AP	Technical Memorandum, "Acceleration of Stress-Migration Failure in Aluminum Interconnect," V. Ryan et al., AT&T Bell Laboratories, June 17, 1992.
50	AQ	Journal of Electronic Materials, Vol. 24, No. 6, 1995, "Enhanced Stress-Migration Reliability for ULSI Interconnect: An Insight into the Perils of Screening Al Depositions Based on Grain Size," V. Ryan et al., pp. 969-974.
ZP.	AR	Circuits and Devices, "Stress-Voiding of Narrow Conductor Lines," F. G. Yost and F. E. Campbell, 1990 IEEE, pp. 40-44.

<sup>\*\*\*</sup>References listed beyond AZ would list as AA-1, AB-2, AC-3 thru AZ-26.

EXAMINER	Evan	Pert	DATE CONSIDERS	126	/o3	

<sup>\*\*\*</sup>Note First Page ONLY Header/Footer. Subsequent pages must ONLY have page # layout as header

<sup>\*</sup>Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609: Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant